

FEATURES

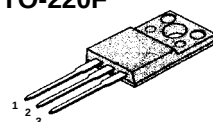
- ❑ Logic-Level Gate Drive
- ❑ Avalanche Rugged Technology
- ❑ Rugged Gate Oxide Technology
- ❑ Lower Input Capacitance
- ❑ Improved Gate Charge
- ❑ Extended Safe Operating Area
- ❑ Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 200V$
- ❑ Lower $R_{DS(ON)}$: 0.145 Ω (Typ.)

$$BV_{DSS} = 200 \text{ V}$$

$$R_{DS(on)} = 0.18 \Omega$$

$$I_D = 9.8 \text{ A}$$

TO-220F



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	200	V
I_D	Continuous Drain Current ($T_C=25^\circ\text{C}$)	9.8	A
	Continuous Drain Current ($T_C=100^\circ\text{C}$)	6.2	
I_{DM}	Drain Current-Pulsed ①	63	A
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy ②	64	mJ
I_{AR}	Avalanche Current ①	18	A
E_{AR}	Repetitive Avalanche Energy ①	4.0	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5	V/ns
P_D	Total Power Dissipation ($T_C=25^\circ\text{C}$)	40	W
	Linear Derating Factor	0.32	
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to +150	$^\circ\text{C}$
T_L	Maximum Lead Temp. for Soldering Purposes, 1/8 " from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	3.13	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient	--	62.5	

Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	200	--	--	V	$V_{GS}=0V, I_D=250\mu A$
$\Delta BV/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.17	--	V/ $^\circ\text{C}$	$I_D=250\mu A$ See Fig 7
$V_{GS(th)}$	Gate Threshold Voltage	1.0	--	2.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
I_{GSS}	Gate-Source Leakage , Forward	--	--	100	nA	$V_{GS}=20V$
	Gate-Source Leakage , Reverse	--	--	-100		$V_{GS}=-20V$
I_{DSS}	Drain-to-Source Leakage Current	--	--	10	μA	$V_{DS}=200V$
		--	--	100		$V_{DS}=160V, T_C=125^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-State Resistance	--	--	0.18	Ω	$V_{GS}=5V, I_D=4.9A$ ④
g_{fs}	Forward Transconductance	--	13.3	--	S	$V_{DS}=40V, I_D=4.9A$ ④
C_{iss}	Input Capacitance	--	1310	1705	pF	$V_{GS}=0V, V_{DS}=25V, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	200	250		
C_{rss}	Reverse Transfer Capacitance	--	95	120		
$t_{d(on)}$	Turn-On Delay Time	--	11	30	ns	$V_{DD}=100V, I_D=18A,$ $R_G=4.6\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	8	25		
$t_{d(off)}$	Turn-Off Delay Time	--	46	100		
t_f	Fall Time	--	15	40		
Q_g	Total Gate Charge	--	40	56	nC	$V_{DS}=160V, V_{GS}=5V,$ $I_D=18A$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	6.8	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	18.6	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_S	Continuous Source Current	--	--	18	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	63		
V_{SD}	Diode Forward Voltage ④	--	--	1.5	V	$T_J=25^\circ\text{C}, I_S=9.8A, V_{GS}=0V$
t_{rr}	Reverse Recovery Time	--	224	--	ns	$T_J=25^\circ\text{C}, I_F=18A$
Q_{rr}	Reverse Recovery Charge	--	1.55	--	μC	

Notes ;

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=1\text{mH}, I_{AS}=9.8A, V_{DD}=50V, R_G=27\Omega$, Starting $T_J=25^\circ\text{C}$
- ③ $I_{SD}\leq 18A, di/dt\leq 260A/\mu s, V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- ④ Pulse Test : Pulse Width = $250\mu s$, Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

Fig 1. Output Characteristics

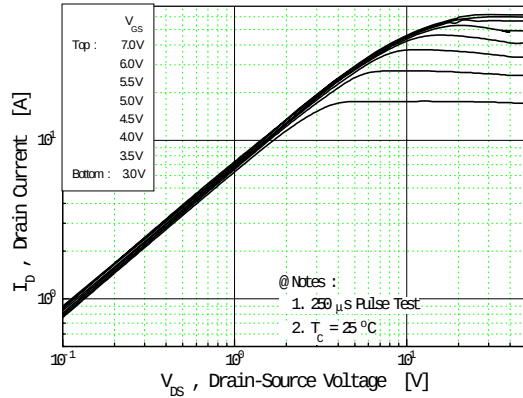


Fig 2. Transfer Characteristics

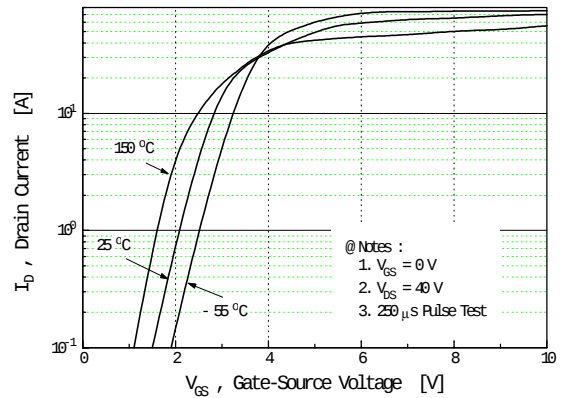


Fig 3. On-Resistance vs. Drain Current

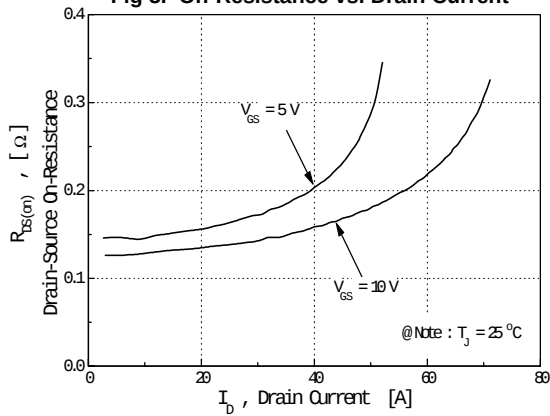


Fig 4. Source-Drain Diode Forward Voltage

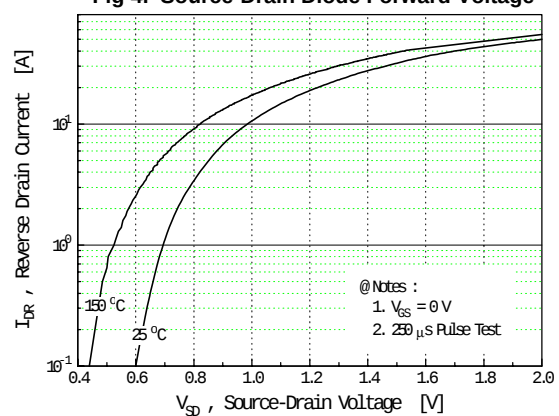


Fig 5. Capacitance vs. Drain-Source Voltage

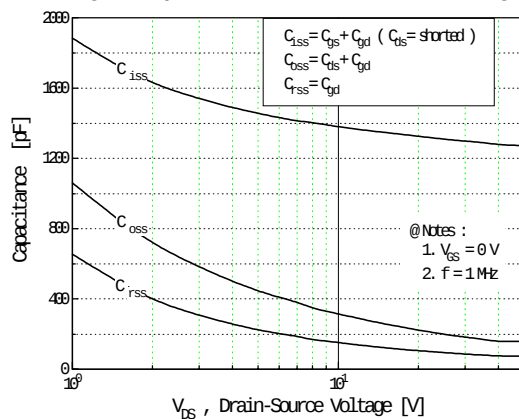
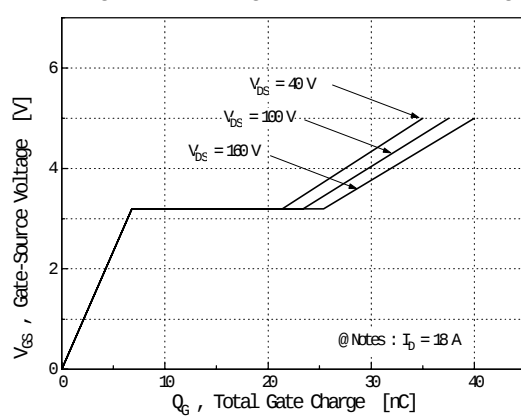


Fig 6. Gate Charge vs. Gate-Source Voltage



IRLS640A

N-CHANNEL POWER MOSFET

Fig 7. Breakdown Voltage vs. Temperature

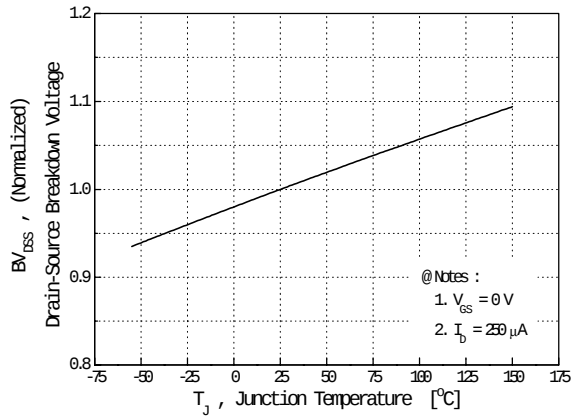


Fig 8. On-Resistance vs. Temperature

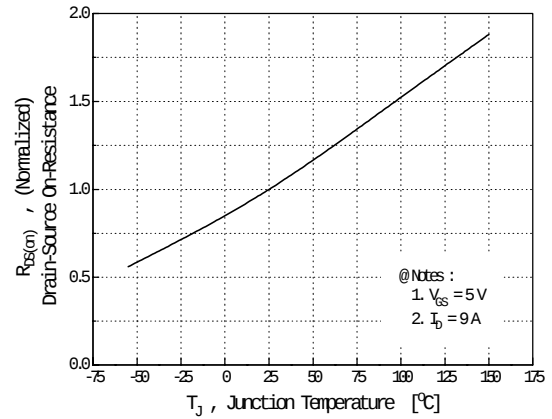


Fig 9. Max. Safe Operating Area

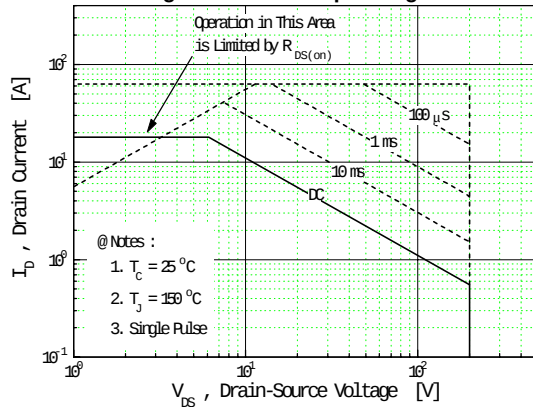


Fig 10. Max. Drain Current vs. Case Temperature

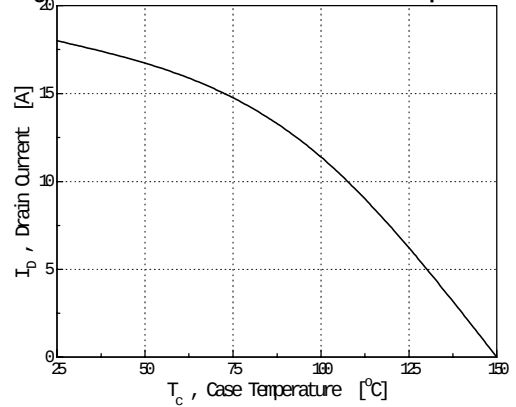


Fig 11. Thermal Response

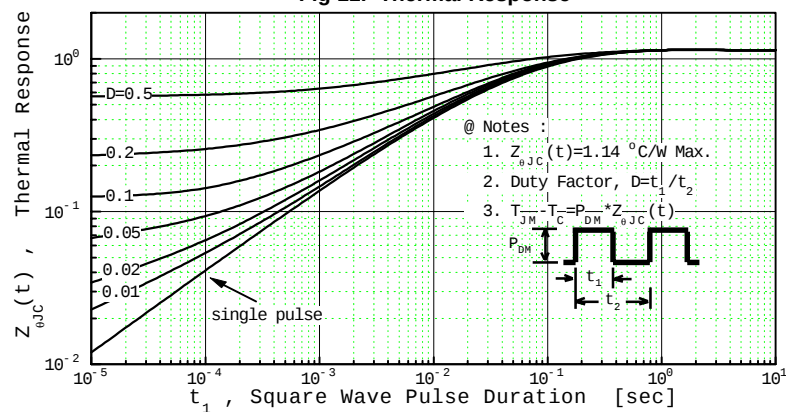


Fig 12. Gate Charge Test Circuit & Waveform

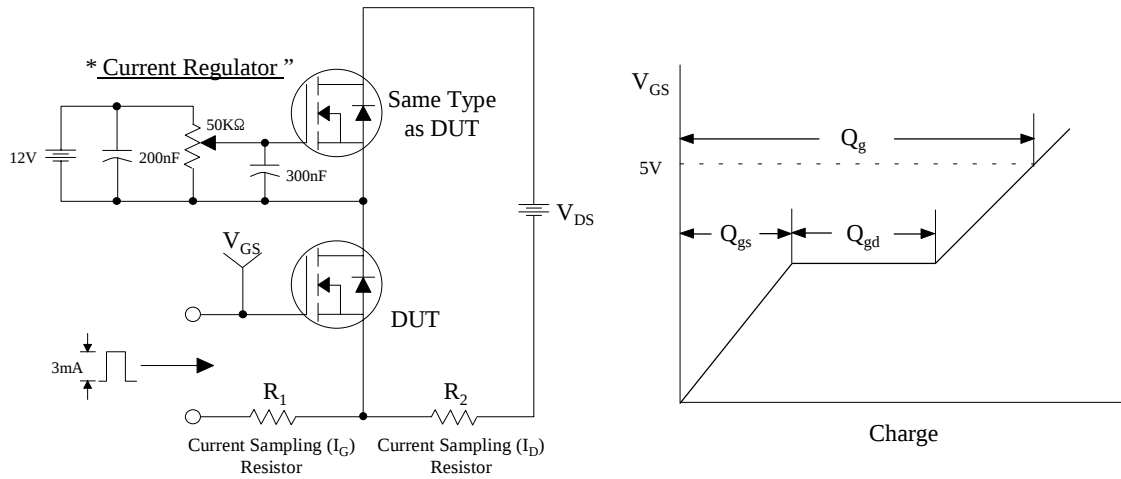


Fig 13. Resistive Switching Test Circuit & Waveforms

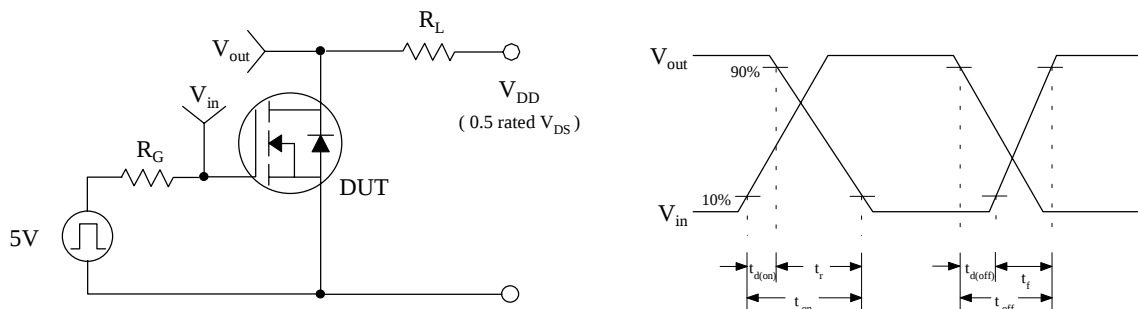


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

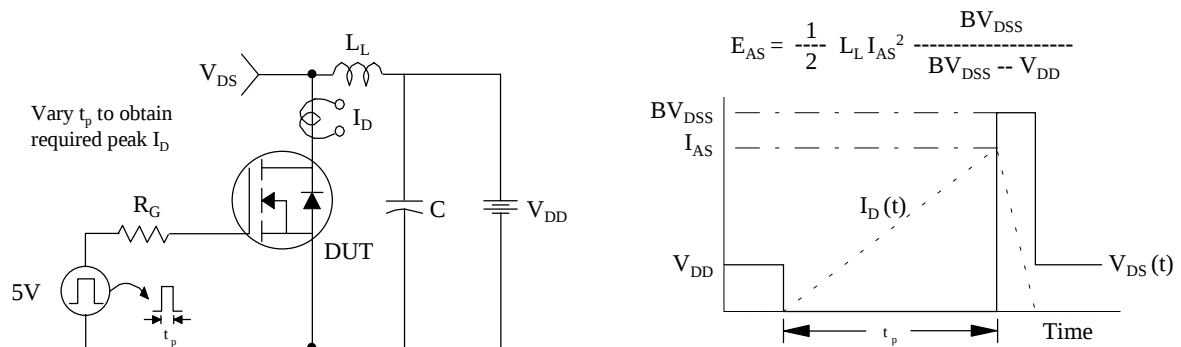
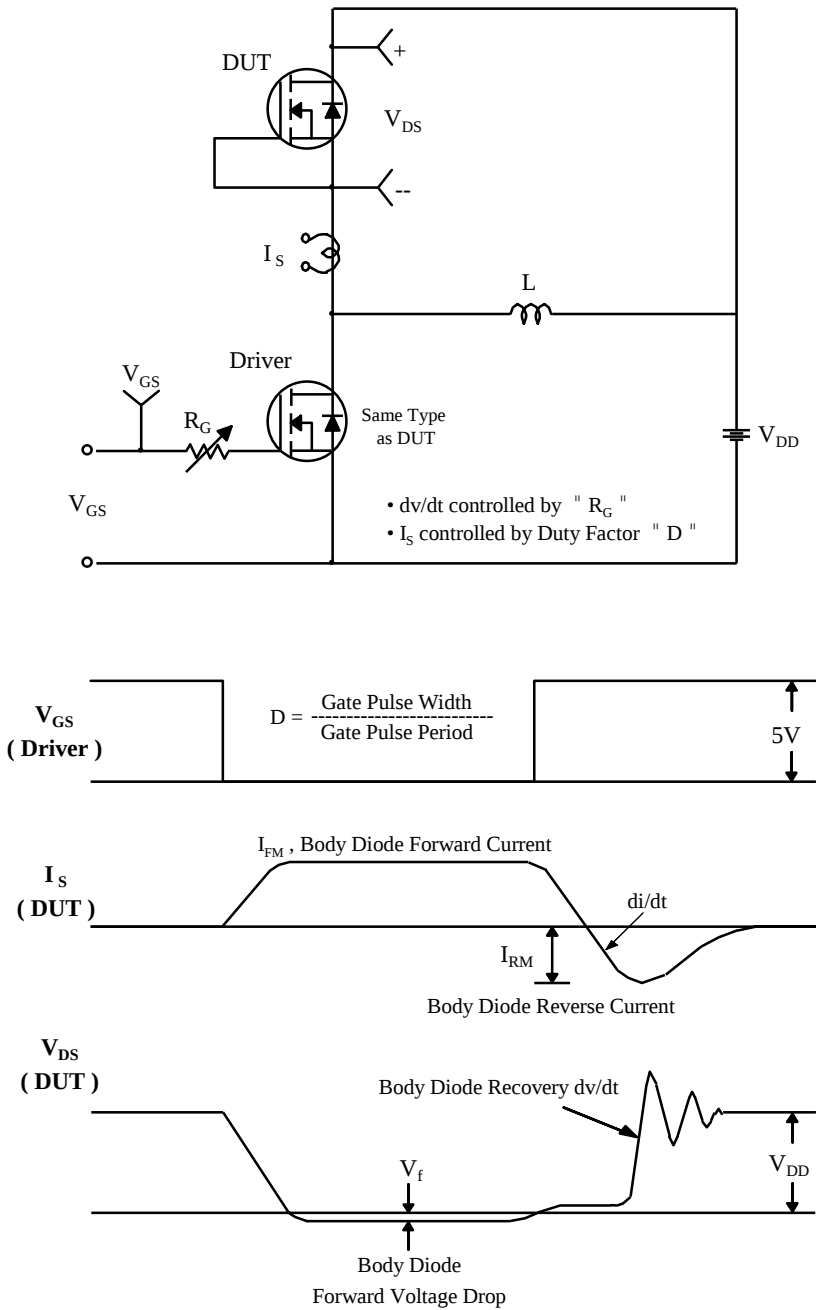


Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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